

RELEASE FILM for Coverlay Lamination ONLY! RCL (TPX-replacement)

RCL – Release Film is a very economical solution to be used for the lamination of coverlay with Quick Lamination machines. The maximum laminating temperature is 185°C for 3 minutes or 165°C for 60 minutes and its own conformal behaviour and reduces residues on circuits and contamination. Due to its excellent conformal behaviour combined with double sided release

function it also can be used together with Silicon rubber pads or other conforming rubber pads!

RCL– Release Film is an inert or non reactive material and leaves no residues on the PCB – surfaces. Excellent functional and dimensional properties under common thermal condition and high pressure guarantees a very easy release after the coverlay lamination process.

PROPERTIES

Thermal Usage in the hot press	max. 190 °C (374 °F) for 100min.	
Softening point	110 °C ± 10 °C	
Density	1.200 gcm ⁻³	ASTM-D1505
Tensile strength	MD ≥ 150 Nmm ⁻² TD ≥ 130 Nmm ⁻²	ASTM D882A ASTM D882A
Elongation at break (v= 50mmmin ⁻¹)	MD ≥ 178 % TD ≥ 63 %	ASTM D882A ASTM D882A
Heat shrinkage (200°C / 10 min.)	MD ≤ 3.4 % TD ≤ 0.5 %	ASTM D2305 ASTM D2305
Coefficient of friction (static) Coefficient of friction (dynamic)	0.25 0.09	ASTM D1894 ASTM D1894
Decomposition temperature	> 240 °C	
Moisture Absorption	< 1,2 % at common room	
Appearance		
Haze	1,8 %	ASTM-D1003
Surface	Smooth - both sides, Ra < 0,3 µm	
Storage Life	> 1 year at room temperature	
Thickness	50 µm – 2.0 mil	
Length of film	1000 / 500 m	
Max. Roll widths	1350 mm	

Subject to changes due to technical improvements without prior notice.

Other dimensions on request.